5 Ø / Descriptions

4.0A n µÉx ì łdý v k V ” UMSB / xo
4.0A Surface Mount Glass Passivated Bridge Rectifier,UMSB thin package.

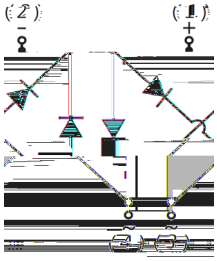
/“ / Features

ì łdý / Ì k F g 9 y < d < k 3 g v y ’ k ‰ , F g ˚ Ö k n µÉx k
)í D }o
Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V,Forward Current: 4.0A, Fast reverse recovery time, Designed for Surface Mount Application, HF product.

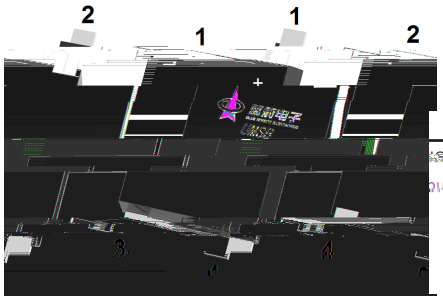
— ÷ / Applications

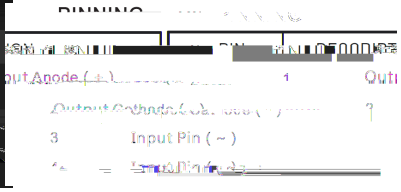
%† " (o
General purpose.

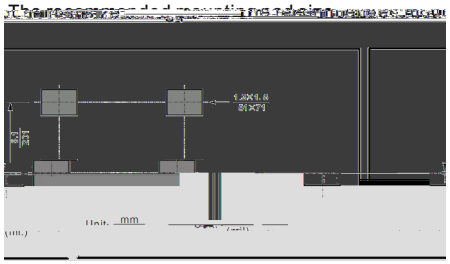
ˆ W] Ô / Equivalent Circuit



Û æ / Pinning





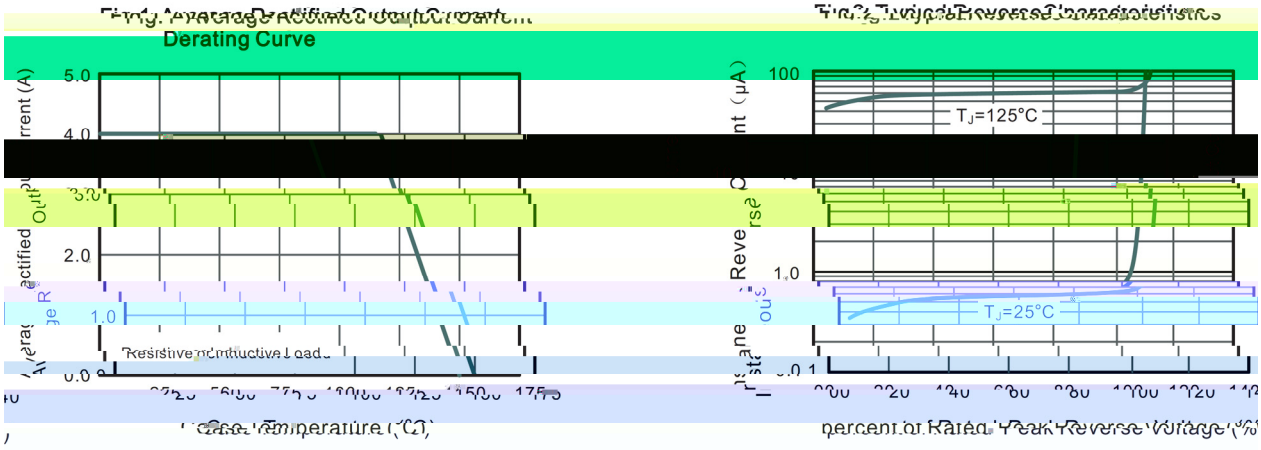


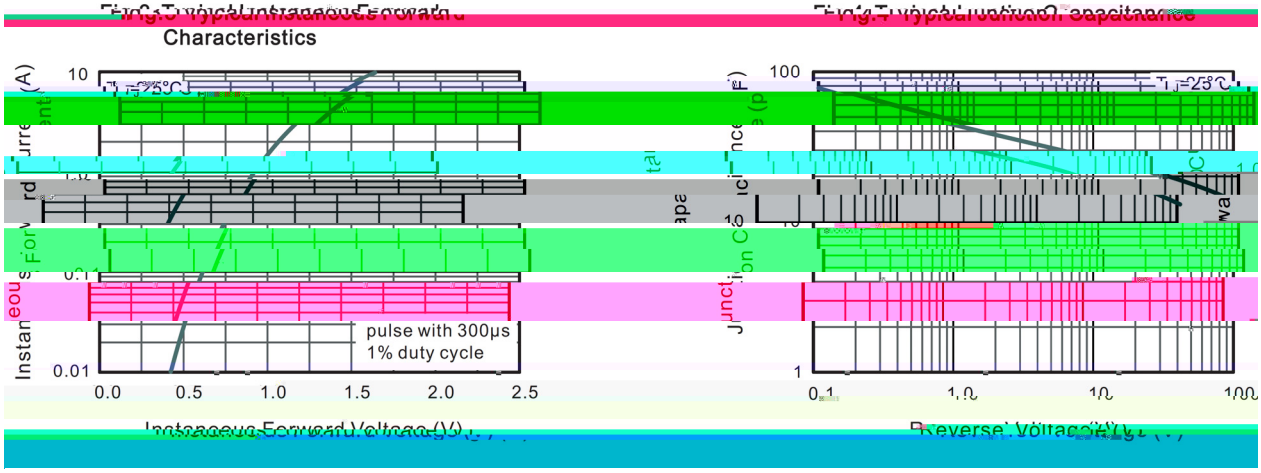
, M V / Marking

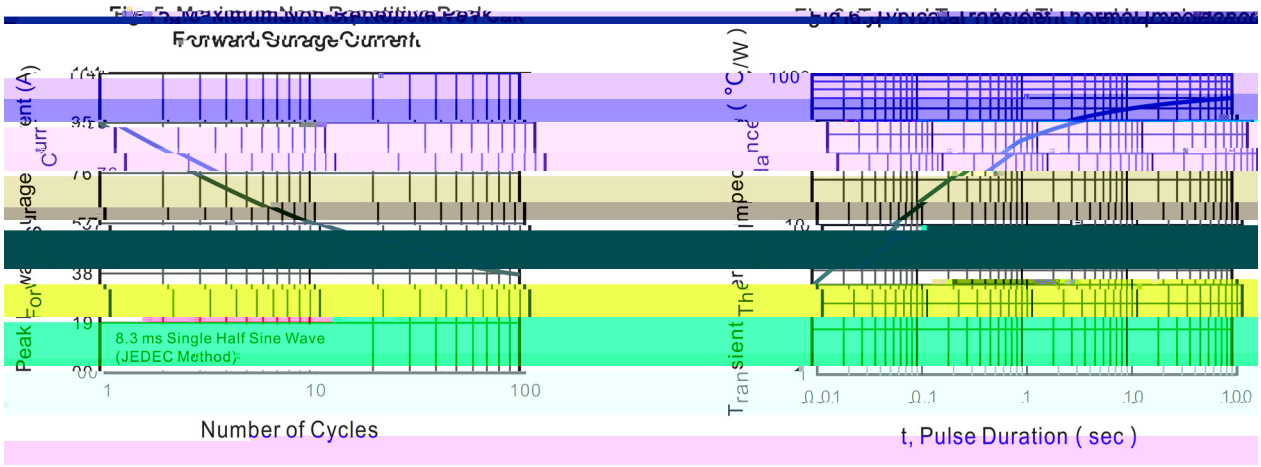
- ~ “ ¢o
See Marking Instructions.

@ Parameter	Z Symbol	Rating						% y Unit
		FMSB40B	FMSB40D	FMSB40G	FMSB40J	FMSB40K	FMSB40M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Tc = 115 -	I_o	4.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	95						A
Typical Junction Capacitance ¯Note1¯	C_j	50						pF
	$R_{\theta JA}$	60						℃/W
[redacted]		15						
	$R_{\theta JL}$	25						
Maximum Reverse Recovery Time ¯Note3¯	t_{rr}	150			250	500		ns
Operating and Storage Temperature Range	T_j,T_{stg}	-55~+150						

Ô? d ¢ / Electrical Characteristic Curve

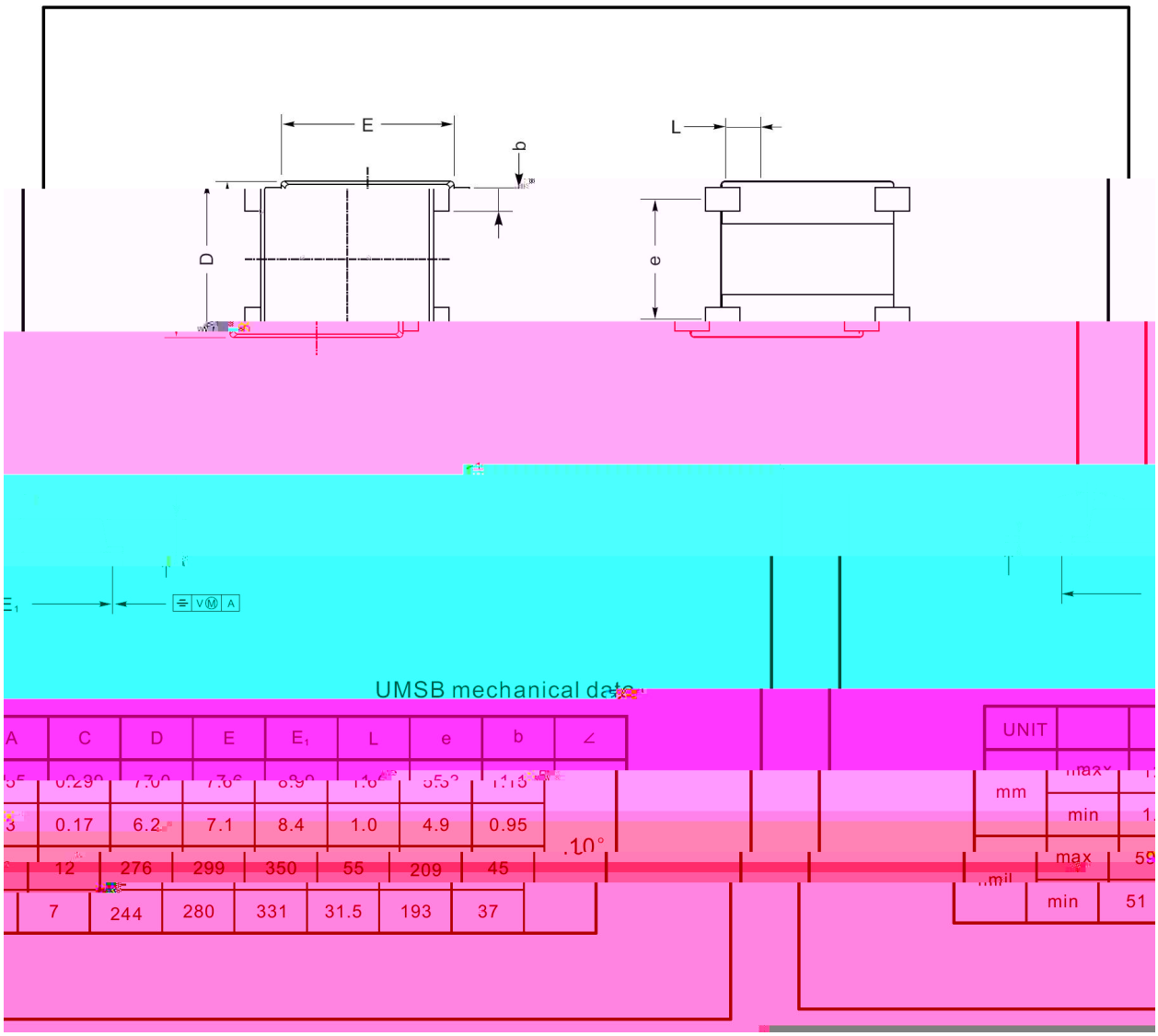






Ø =) ¢ / Package Dimensions

UMSB

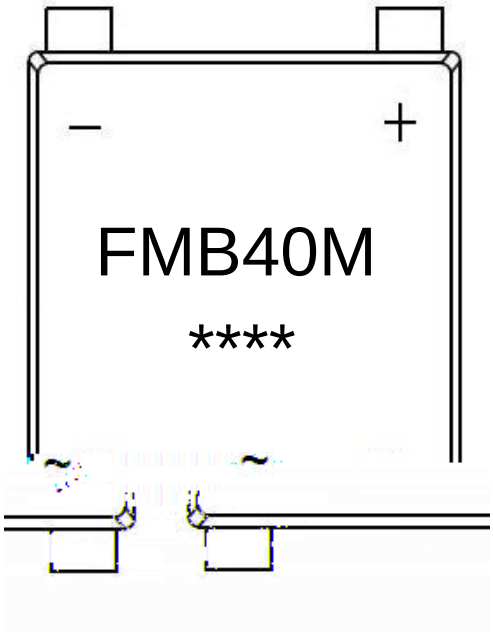


UMSB mechanical data

A	C	D	E	E_1	L	e	b	∠
3	0.17	6.2	7.1	8.4	1.0	4.9	0.95	10°
	12	276	299	350	55	209	45	
	7	244	280	331	31.5	193	37	

UNIT		
mm	min	1
	max	59
mil	min	51

, M y / Marking Instructions



“ ¢

FMB40M y ” Z W A

**** y ÿD Z W A k ÿD Z J

Note:

FMB4OM y Product Type Code

**** y 2 U Z 4 U) U J K I U J K I N G T M K] O Z N 2 U Z 4 U

Marking

Type number	Marking code
FMSB40B	FMB40B
FMSB40D	FMB40D
FMSB40G	FMB40G
FMSB40J	FMB40J
FMSB40K	FMB40K
FMSB40M	FMB40M

WD t ¢ (x/) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

“¢y	Note:
1o ˜‰ 150 ‰180 - k 60 ‰90sec;	1.Preheating:150~180 - , Time:60~90sec.
2o Q 245 r5 - k 4 Ò 5 r0.5sec;	2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.
3o D N òi Ò0 , 2 ‰10 - /sec.	3. Cooling Speed: 2~10 - /sec.

´D /C^{a} p fl »] / Resistance to Soldering Heat Test Conditions

y 260 r5 - y 10 r1 sec. Temp.:260±5 Time:10±1 sec

G P Æ / Packaging SPEC.

2 & x / REEL

Package Type 7>ß E	Units ;>ß ƒH	Dimension ;>ß p . (unit ˇ mm³)